

FEE TRANSMITTAL

Electronic Version 1.1.0

Stylesheet Version: 1.0

Patent fees are subject to annual revisions on or about October 1st of each year.

Large Entity

TOTAL FEES AUTHORIZED: \$ 780

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Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

SUBMITTED BY

Authorized Name: WINSTON HSU
Electronic Signature Mark: VAEB-JMXX-8IIL
Date Signed: 20021031

BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	1001	\$ 740

Subtotal For Basic Filing Fee: \$ 740

EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 10	1202	\$ 18	0	\$ 0
Independent Claims: 3	1201	\$ 84	0	\$ 0

Subtotal For Extra Claims Fees: \$ 0

ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40

Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 19372
Application ID: 10065568
Title of Invention: SOLDER BUMP STRUCTURE AND
LASER REPAIR PROCESS FOR
MEMORY DEVICE
First Named Inventor: Kuo-Ming Chen
Domestic/Foreign Application: Domestic Application
Filing Date: null
Effective Receipt Date: 2002-10-31
Submission Type: Utility Patent Filing
Filing Type: new-utility
Confirmation Number: 0
Attorney Docket Number: NAUP0482USA
Digital Certificate Holder: cn=Winston Hsu, ou=Registered Attorneys, ou=Patent and
Trademark Office, ou=Department of Commerce; o=U.S.
Government, c=US
Certificate Message Digest: zq0+veBWgFxxKnpwjk/UGA==
Total Fees Authorized: \$780.0
Payment Category: DA - Deposit Account
Deposit Account Number: 500801
Deposit Account Name: WINSTON HSU





TRANSMITTAL FORM

Electronic Version 1.0.3

Stylesheet Version: 1.0

Attorney Docket
Number:

NAUP0482USA

Submission Type: Utility
Patent Filing

SOLDER BUMP STRUCTURE AND LASER REPAIR PROCESS FOR MEMORY DEVICE

First Named Inventor: Kuo-Ming Chen

SUBMITTED BY

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Attached Files:

declaration	NAUP0482DEC1.TIF
declaration	NAUP0482DEC2.TIF
specification	NAUP0482.xml
bibd-transmittal	NAUP0482apds.xml
patent-assignments	NAUP0482asgn.xml
fee-transmittal	NAUP0482fee.xml

Attached Image File(s):

NAUP0482DEC1.TIF
NAUP0482DEC2.TIF

Comments:

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